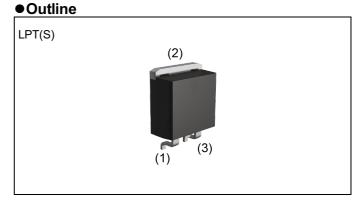
### Nch 650V 9A Power MOSFET

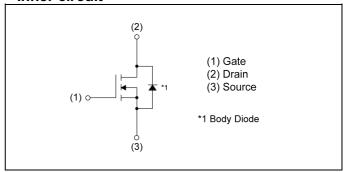
V <sub>DSS</sub>	650V
R <sub>DS(on)</sub> (Max.)	0.585Ω
I <sub>D</sub>	±9A
$P_{D}$	94W

Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant



### •Inner circuit



### Application

Switching

### Packaging specifications

Packing	Embossed Tape
Packing code	TL
Marking	R6509ENJ
Basic ordering unit (pcs)	1000

### ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		$V_{DSS}$	650	V
Continuous drain current (T <sub>c</sub> = 25	5°C)	I <sub>D</sub> *1	±9	А
Pulsed drain current	I <sub>DP</sub> *2	±27	А	
0.1.0	static	V <sub>GSS</sub>	±20	V
Gate - Source voltage	AC(f>1Hz)		±30	V
Avalanche current, single pulse	<u>,</u>	I <sub>AS</sub>	1.4	Α
Avalanche energy, single pulse		E <sub>AS</sub> *3	158	mJ
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	94	W	
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage te	T <sub>stg</sub>	-55 to +150	°C	

### ●Thermal resistance

Dougrantou	Curah al	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *4	-	-	1.3	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *5	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# • Electrical characteristics ( $T_a = 25$ °C)

Davameter	Cymah al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	650	-	-	V
		V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V				
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μΑ
		$T_j = 125^{\circ}C$	ı	-	1000	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	1	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 230 \mu A$	2	-	4	V
		$V_{GS} = 10V, I_D = 2.8A$				
Static drain - source on - state resistance	R <sub>DS(on)</sub> *6	$T_j = 25^{\circ}C$	-	0.530	0.585	Ω
		$T_j = 125^{\circ}C$	-	-	1	
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	10	-	Ω

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	430	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	580	1	pF
Reverse transfer capacitance	$C_{rss}$	f = 1MHz	-	65	1	
Turn - on delay time	$t_{d(on)}^{*6}$	$V_{DD} \simeq 300V$ , $V_{GS} = 10V$	-	20	1	
Rise time	<b>t</b> <sub>r</sub> *6	I <sub>D</sub> = 4.5A	-	30	1	no
Turn - off delay time	t <sub>d(off)</sub> *6	$R_L \simeq 66.7\Omega$	_	70	- 1	ns
Fall time	<b>t</b> <sub>f</sub> *6	$R_G = 10\Omega$	-	25	-	

### ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Davamatar	C: reals al	Conditions	Values			1.1:4
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q <sub>g</sub> *6	V <sub>DD</sub> ≈ 300V	-	24	-	
Gate - Source charge	Q <sub>gs</sub> *6	I <sub>D</sub> = 9A	-	4	-	nC
Gate - Drain charge	Q <sub>gd</sub> *6	V <sub>GS</sub> = 10V	-	12	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 300V, I <sub>D</sub> = 9.0A	-	6.2	-	V

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $\doteqdot$ 100mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>i</sub>=25 $^{\circ}$ C

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*5</sup> Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)

<sup>\*6</sup> Pulsed

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Source current	I <sub>S</sub> *1	T <sub>C</sub> = 25°C	1	-	9	Α
Pulsed source current	I <sub>SP</sub> *2	1C - 23 C	1	-	27	Α
Source-Drain voltage	V <sub>SD</sub> *6	$V_{GS} = 0V, I_{S} = 9.0A$	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *6		-	400	-	ns
Reverse recovery charge	Q <sub>rr</sub> *6	I <sub>S</sub> = 9A di/dt = 100A/µs		4	-	μC
Peak reverse recovery current	I <sub>rr</sub> *6		-	20	-	Α

Fig.1 Power Dissipation Derating Curve

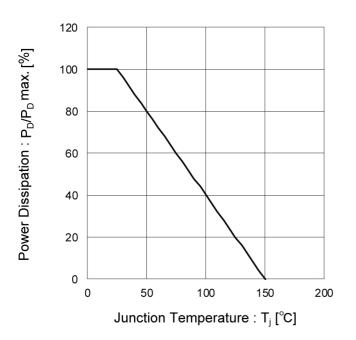


Fig.2 Drain Current Derating Curve

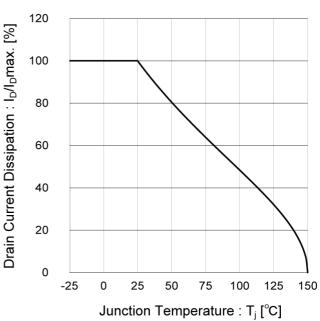


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

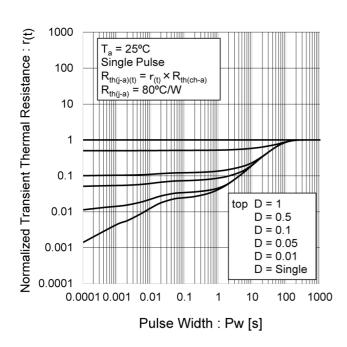
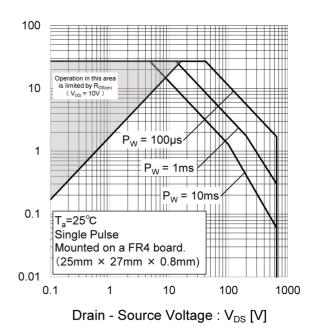


Fig.4 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

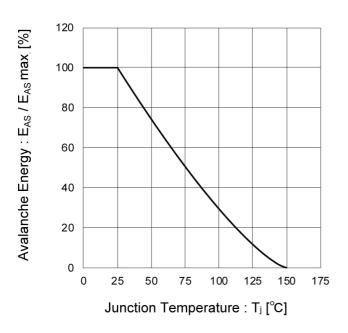


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

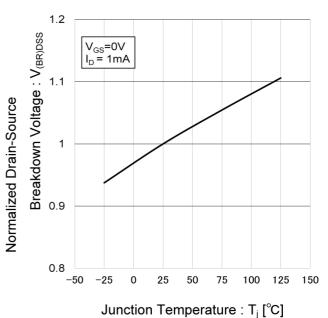


Fig.7 Typical Output Characteristics(I)

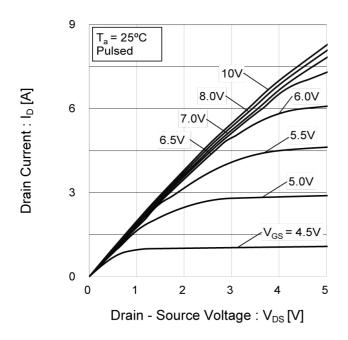
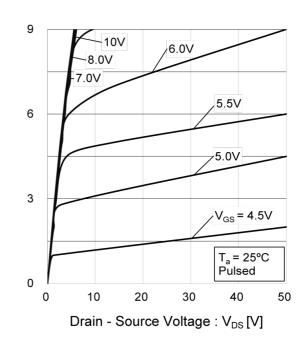


Fig.8 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Fig.9 Typical Transfer Characteristics

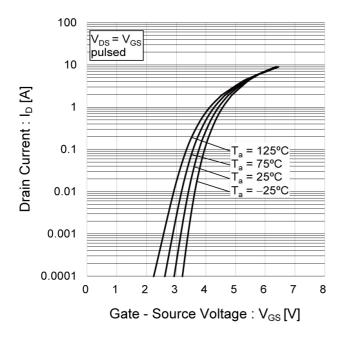


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

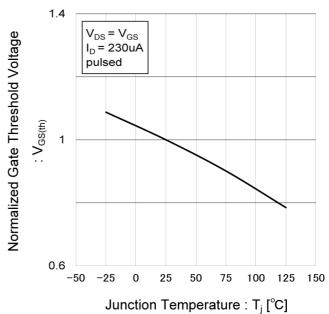


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

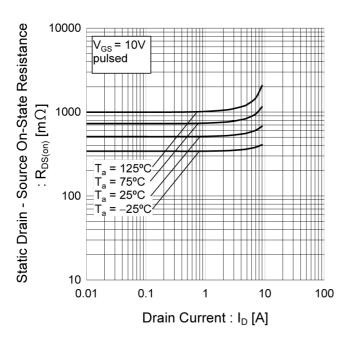


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

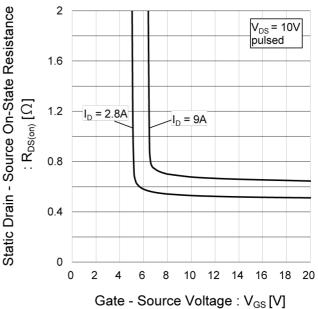


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

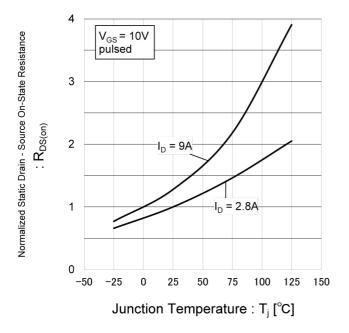


Fig.14 Typical Capacitance vs.

Drain - Source Voltage

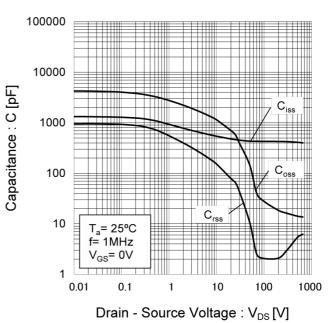


Fig.15 Switching Characteristics

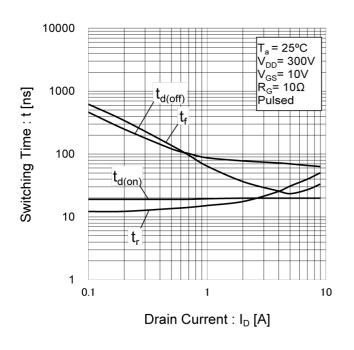
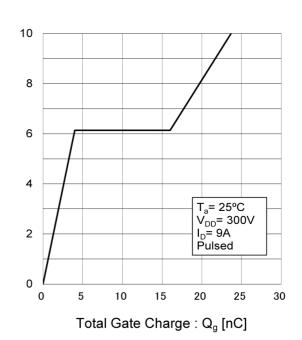
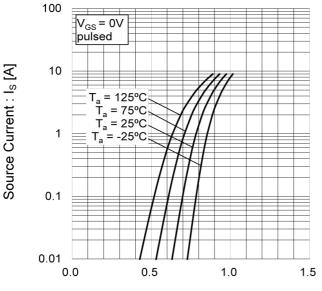


Fig.16 Typical Gate Charge



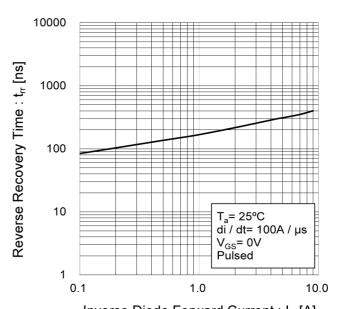
Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.17 Source Current vs. Source - Drain Voltage



Source - Drain Voltage : V<sub>SD</sub> [V]

Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current : I<sub>S</sub> [A]

#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

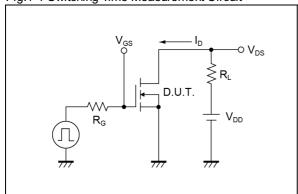


Fig.2-1 Gate Charge Measurement Circuit

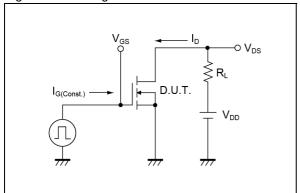


Fig.3-1 Avalanche Measurement Circuit

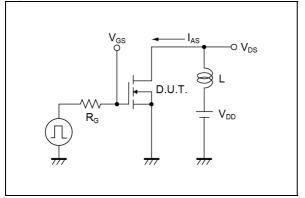


Fig.4-1 trr Measurement Circuit

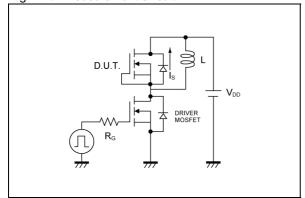


Fig.1-2 Switching Waveforms

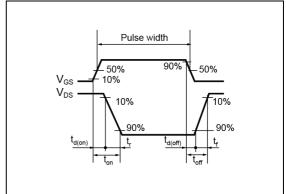


Fig.2-2 Gate Charge Waveform

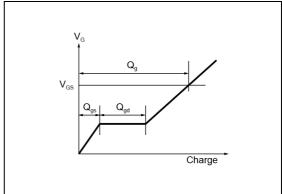


Fig.3-2 Avalanche Waveform

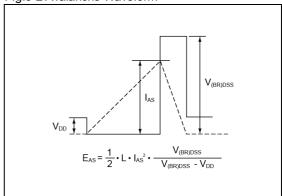
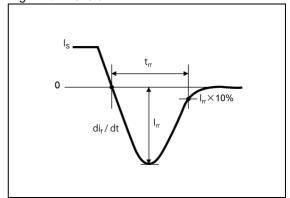
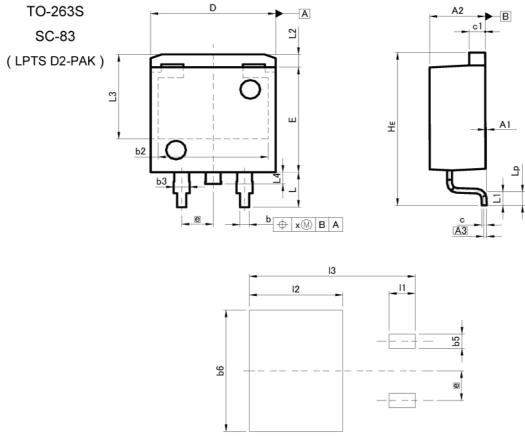


Fig.4-2 trr Waveform



### Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.	20	0.0	47
L2	1.	10	0.0	43
L3	7.25		0.285	
L4	1.00		0.0	39
Lp	0.90	1.50	0.035	0.059
Х	-	0.25	-	0.010
		100 100 100 100 100 100 100 100 100 100		
1		ETERO	1110	150

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b5	-	1.23	-	0.049
b6	_	10.40	-	0.409
. 11		2.10	1	0.083
12	-	7.55	-	0.297
13		13.40	i —	0.528

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CL ACCIII	CLASS II b	CI VCCIII
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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# R6509ENJ - Web Page

Part Number	R6509ENJ
Package	LPTS (D2PAK)
Unit Quantity	1000
Minimum Package Quantity	1000
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes